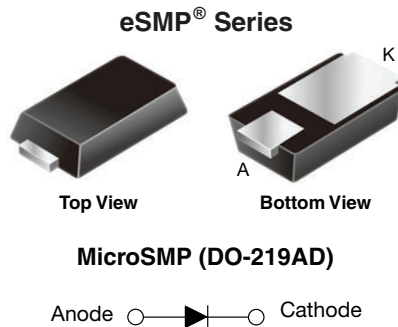


# Surface-Mount TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifier



## FEATURES

- Very low profile - typical height of 0.65 mm
- Ideal for automated placement
- Trench MOS Schottky technology
- Low forward voltage drop
- Low power loss, high efficiency
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
  - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

 AUTOMOTIVE  
GRADE  
Available

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## LINKS TO ADDITIONAL RESOURCES


[3D Models](#)

### PRIMARY CHARACTERISTICS

$I_{F(AV)}$	2 A
$V_{RRM}$	150 V
$I_{FSM}$	30 A
$V_F$ at $I_F = 2$ A (125 °C)	0.68 V
$T_J$ max.	175 °C
Package	MicroSMP (DO-219AD)
Circuit configuration	Single

## TYPICAL APPLICATIONS

For use in low voltage high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications, in commercial, industrial, and automotive applications.

## MECHANICAL DATA

**Case:** MicroSMP (DO-219AD)

Molding compound meets UL 94 V-0 flammability rating  
Base P/N-M3 - halogen-free, and RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

**Polarity:** Color band denotes the cathode end

### MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)

PARAMETER	SYMBOL	V2PM12	UNIT
Device marking code		2MC	
Maximum repetitive peak reverse voltage	$V_{RRM}$	150	V
Maximum DC forward current	$I_{F(AV)}$ <sup>(1)</sup>	1.3	A
	$I_{F(AV)}$ <sup>(2)</sup>	2	A
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	$I_{FSM}$	30	A
Operating junction and storage temperature range	$T_J$ <sup>(3)</sup> , $T_{STG}$	-40 to +175	°C

#### Notes

<sup>(1)</sup> Free air, mounted on recommended copper pad area

<sup>(2)</sup> Mounted on 8.0 mm x 8.0 mm pad area

<sup>(3)</sup> The heat generated must be less than the thermal conductivity from junction to ambient:  $dP_D/dT_J < 1/R_{\theta JA}$

<b>ELECTRICAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	$I_F = 1.0\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.91	-	V
	$I_F = 2.0\text{ A}$			1.33	1.41	
	$I_F = 1.0\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.6	-	
	$I_F = 2.0\text{ A}$			0.68	0.76	
Reverse current	$V_R = 100\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	0.001	-	mA
		$T_A = 125\text{ }^\circ\text{C}$		0.25	-	
	$V_R = 150\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$		-	0.05	
		$T_A = 125\text{ }^\circ\text{C}$		0.5	2	
Typical junction capacitance	4.0 V, 1 MHz		$C_J$	100	-	pF

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle  
 (2) Pulse test: pulse width  $\leq 5\text{ ms}$

<b>THERMAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	V2PM15	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)(2)}$	130	$^\circ\text{C/W}$
	$R_{\theta JM}^{(3)}$	20	

**Notes**

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$   
 (2) Free air, mounted on FR4 PCB, 2 oz. standard footprint,  $R_{\theta JA}$  - junction to ambient  
 (3) Mounted on PCB with 8.0 mm x 8.0 mm copper pad areas,  $R_{\theta JM}$  - junction to mount

<b>ORDERING INFORMATION</b> (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V2PM15-M3/H	0.006	H	4500	7" diameter plastic tape and reel
V2PM15HM3/H <sup>(1)</sup>	0.006	H	4500	7" diameter plastic tape and reel

**Note**

- (1) AEC-Q101 qualified

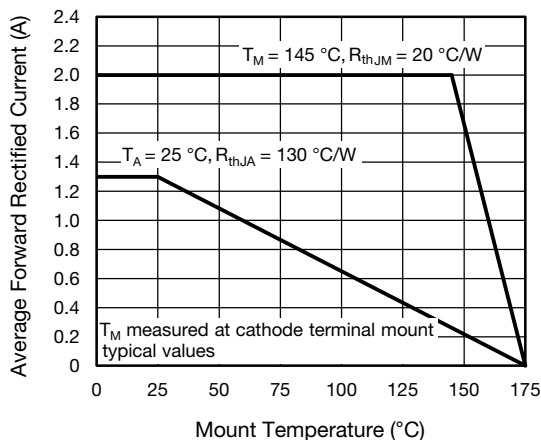
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

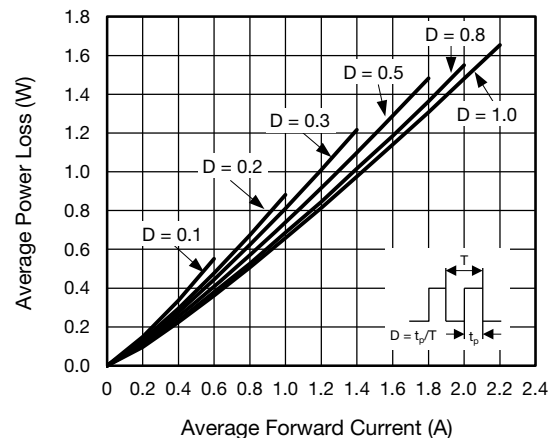


Fig. 2 - Average Power Loss Characteristics

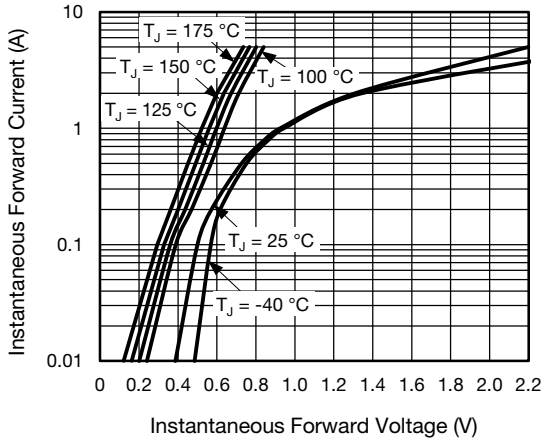


Fig. 3 - Typical Instantaneous Forward Characteristics

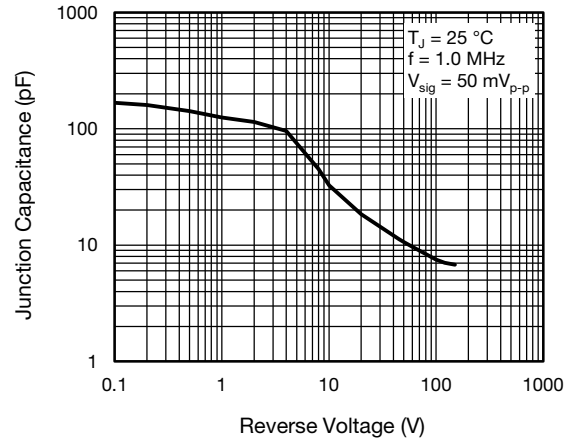


Fig. 5 - Typical Junction Capacitance

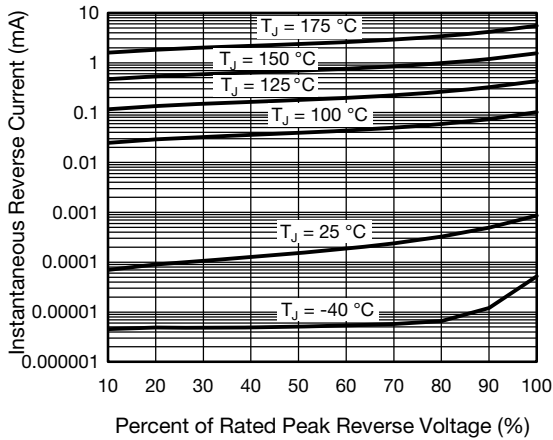


Fig. 4 - Typical Reverse Leakage Characteristics

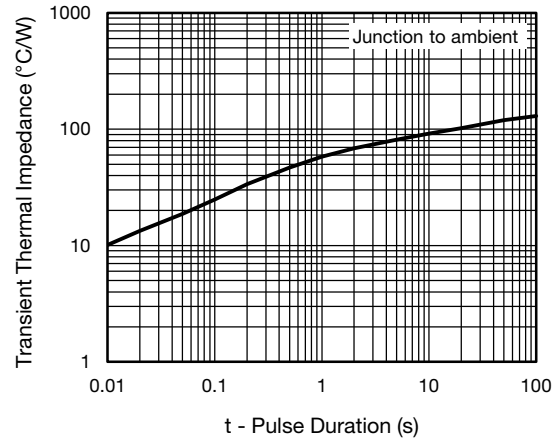
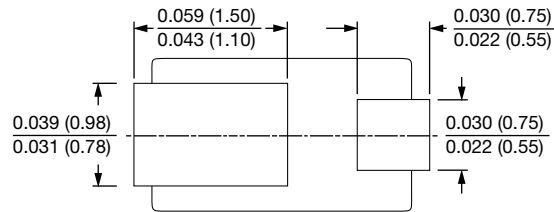
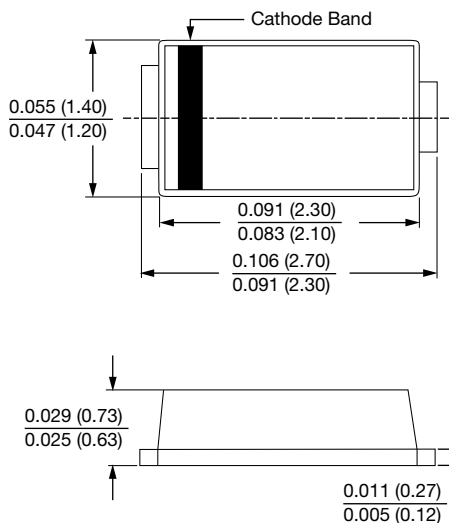


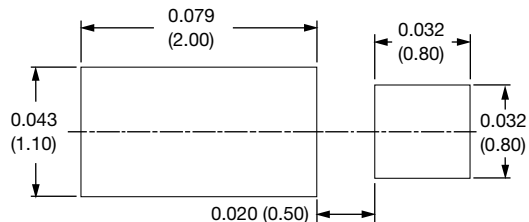
Fig. 6 - Typical Transient Thermal Impedance

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)

**MicroSMP (DO-219AD)**



**Mounting Pad Layout**





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